

# **BUK9K35-60E**

# Dual N-channel 60 V, 35 m $\Omega$ logic level MOSFET

**12 November 2014** 

Product data sheet

## 1. General description

Dual logic level N-channel MOSFET in an LFPAK56D (Dual Power-SO8) package using TrenchMOS technology. This product has been designed and qualified to AEC Q101 standard for use in high performance automotive applications.

#### 2. Features and benefits

- Dual MOSFET
- Q101 Compliant
- Repetitive avalanche rated
- Suitable for thermally demanding environments due to 175 °C rating
- True logic level gate with V<sub>GS(th)</sub> rating of greater than 0.5 V at 175 °C

## 3. Applications

- 12 V Automotive systems
- Motors, lamps and solenoid control
- Transmission control
- Ultra high performance power switching

#### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit		
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 175 °C		-	-	60	V		
I <sub>D</sub>	drain current	V <sub>GS</sub> = 5 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>		-	-	22	Α		
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	-	38	W		
Static characte	Static characteristics FET1 and FET2								
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 5 \text{ A}; T_j = 25 \text{ °C}; Fig. 12$		-	30.5	35	mΩ		
Dynamic chara	Dynamic characteristics FET1 and FET2								
$Q_{GD}$	gate-drain charge	$I_D = 5 \text{ A}; V_{DS} = 48 \text{ V}; V_{GS} = 5 \text{ V};$ $T_j = 25 \text{ °C}; Fig. 14; Fig. 15$		-	3	-	nC		



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# **Pinning information**

Table 2. **Pinning information** 

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S1	source1	8 7 6 5	D1 D1 D2 D2
2	G1	gate1	S1 G1	
3	S2	source2		
4	G2	gate2		
5	D2	drain2		
6	D2	drain2		mbk725
7	D1	drain1	1 2 3 4 LFPAK56D (SOT1205)	
8	D1	drain1	2	

# **Ordering information**

Table 3. **Ordering information** 

Type number	Package					
	Name	Description	Version			
BUK9K35-60E	LFPAK56D	Plastic single ended surface mounted package (LFPAK56D); 8 leads	SOT1205			

#### **Marking** 7.

Table 4. **Marking codes** 

Type number	Marking code
BUK9K35-60E	93560E

#### **Limiting values** 8.

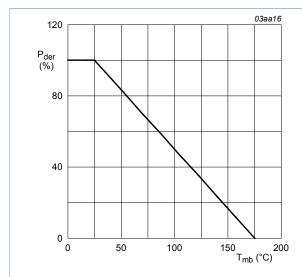
**Limiting values** Table 5.

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 175 °C		-	60	V
$V_{DGR}$	drain-gate voltage	$R_{GS}$ = 20 kΩ; $T_j \ge 25$ °C; $T_j \le 175$ °C		-	60	V
$V_{GS}$	gate-source voltage	T <sub>j</sub> ≤ 175 °C; DC		-10	10	V
		T <sub>j</sub> ≤ 175 °C	[1][2]	-15	15	V
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	38	W
I <sub>D</sub>	drain current	T <sub>mb</sub> = 25 °C; V <sub>GS</sub> = 5 V; <u>Fig. 2</u>		-	22	Α
		$T_{mb}$ = 100 °C; $V_{GS}$ = 5 V; <u>Fig. 2</u>		-	16	Α
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Symbol	Parameter	Conditions		Min	Max	Unit
I <sub>DM</sub>	peak drain current	$T_{mb}$ = 25 °C; pulsed; $t_p \le 10 \mu s$ ; Fig. 3		-	90	Α
T <sub>stg</sub>	storage temperature			-55	175	°C
Tj	junction temperature			-55	175	°C
$T_{sld(M)}$	peak soldering temperature			-	260	°C
Source-dra	in diode FET1 and FET2		'			
I <sub>S</sub>	source current	T <sub>mb</sub> 25 °C		-	22	Α
I <sub>SM</sub>	peak source current	pulsed; t <sub>p</sub> ≤ 10 μs; T <sub>mb</sub> = 25 °C		-	90	Α
Avalanche	ruggedness FET1 and FET2					
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$I_D = 22 \text{ A; } V_{sup} \le 60 \text{ V; } V_{GS} = 5 \text{ V;}$ $T_{j(init)} = 25 \text{ °C; } Fig. 4$	[3][4]	-	19.5	mJ

- Accumulated Pulse duration up to 50 hours delivers zero defect ppm.
- Significantly longer life times are achieved by lowering  $T_i$  and or  $V_{\text{GS}}$ [2]
- Refer to application note AN10273 for further information
- [3] [4] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C



Normalized total power dissipation as a Fig. 1. function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100 \%$$

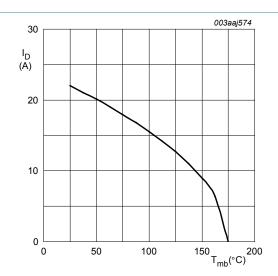


Fig. 2. Continuous drain current as a function of mounting base temperature

$$V_{GS} \ge 5V$$

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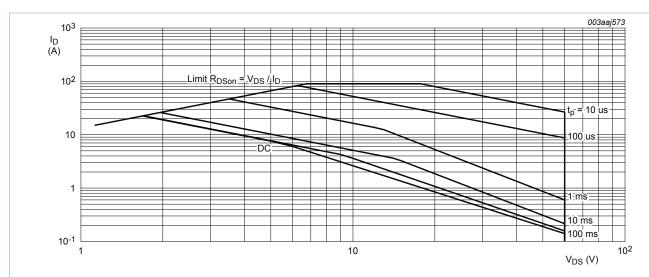


Fig. 3. Safe operating area; continuous and peak drain current as a function of drain-source voltage

$$T_{mb} = 25 \,^{\circ}C; I_{DM}$$
 is single pulse

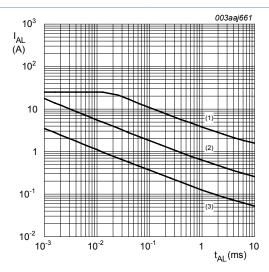


Fig. 4. Single-pulse and repetitive avalanche rating; avalanche current as a function of avalanche time, FET1 and FET2

- (1) Single-pulse;  $T_j = 25 \,^{\circ}C$ .
- (2) Single-pulse;  $T_j = 150 \,^{\circ}C$ .
  - (3) Repetitive.

### 9. Thermal characteristics

Table 6. Thermal characteristics

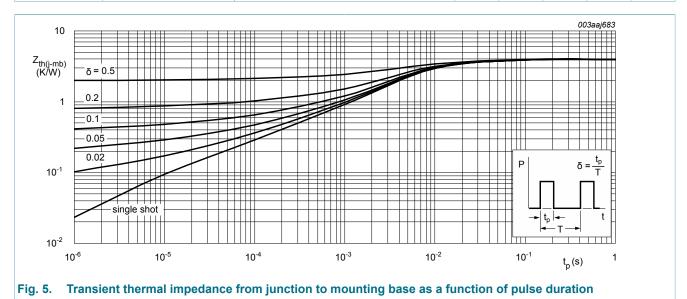
Table of Thornal ordinatorious							
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 5		-	-	3.96	K/W

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	Minimum footprint; mounted on a printed circuit board	-	95	-	K/W



## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics FET1 and FET2					,
V <sub>(BR)DSS</sub>	drain-source	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 °C$	54	-	-	V
	breakdown voltage	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	60	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C; Fig. 10; Fig. 11	1.4	1.7	2.1	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 175 °C; Fig. 10; Fig. 11	0.5	-	-	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = -55 °C; Fig. 10; Fig. 11	-	-	2.45	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 60 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 175 °C	-	-	500	μΑ
		V <sub>DS</sub> = 60 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	0.02	1	μΑ
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	2	100	nA
		V <sub>GS</sub> = 10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	2	100	nA
R <sub>DSon</sub>	drain-source on-state	V <sub>GS</sub> = 5 V; I <sub>D</sub> = 5 A; T <sub>j</sub> = 25 °C; <u>Fig. 12</u>	-	30.5	35	mΩ
	resistance	V <sub>GS</sub> = 5 V; I <sub>D</sub> = 5 A; T <sub>j</sub> = 175 °C; Fig. 12; Fig. 13	-	65.27	79	mΩ
		$V_{GS}$ = 10 V; $I_D$ = 5 A; $T_j$ = 25 °C; <u>Fig. 12</u>	-	26.8	32	mΩ
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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Dynamic cl	haracteristics FET1 and FE	T2				
Q <sub>G(tot)</sub>	total gate charge	$I_D = 5 \text{ A}; V_{DS} = 48 \text{ V}; V_{GS} = 5 \text{ V};$	-	7.8	-	nC
Q <sub>GS</sub>	gate-source charge	T <sub>j</sub> = 25 °C; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	1.2	-	nC
Q <sub>GD</sub>	gate-drain charge		-	3	-	nC
C <sub>iss</sub>	input capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 25 V; f = 1 MHz;	-	811	1081	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; <u>Fig. 16</u>	-	98	118	pF
C <sub>rss</sub>	reverse transfer capacitance		-	51	70	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS}$ = 48 V; $R_{L}$ = 10 $\Omega$ ; $V_{GS}$ = 5 V;	-	7.1	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 5 \Omega; T_j = 25 °C; I_D = 5 A$	-	11.3	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	14.9	-	ns
t <sub>f</sub>	fall time		-	10.6	-	ns
Source-dra	in diode FET1 and FET2		l			
V <sub>SD</sub>	source-drain voltage	$I_S = 10 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}; Fig. 17$	-	0.78	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = 5 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$	-	17.6	-	ns
Q <sub>r</sub>	recovered charge	V <sub>DS</sub> = 30 V; T <sub>j</sub> = 25 °C	-	12.1	-	nC

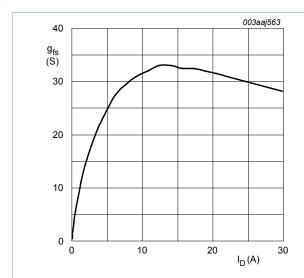


Fig. 6. Forward transconductance as a function of drain current; typical values

$$T_j = 25 \,^{\circ}C; V_{DS} = 15 \, V$$

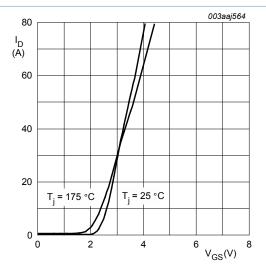


Fig. 7. Transfer Characteristic: drain current as a function of gate-source voltage; typical values

$$V_{DS} = 10V$$

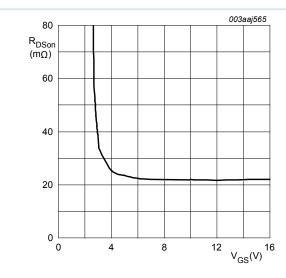


Fig. 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

$$T_j = 25 \,^{\circ}C; I_D = 5A$$

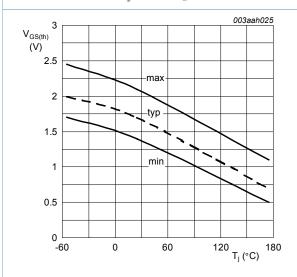


Fig. 10. Gate-source threshold voltage as a function of junction temperature

$$I_D = 1 \text{ mA}; \ V_{DS} = V_{GS}$$

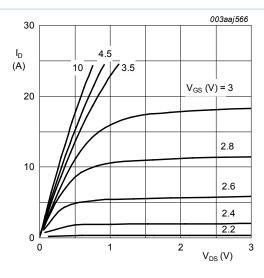


Fig. 9. Output characteristics: drain current as a function of drain-source voltage; typical values

$$T_j = 25 \,^{\circ}C$$

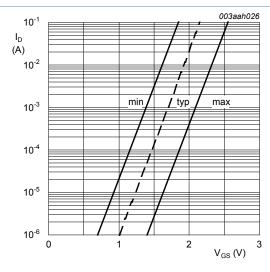


Fig. 11. Sub-threshold drain current as a function of gate-source voltage

$$T_j = 25$$
°C;  $V_{DS} = 5V$ 

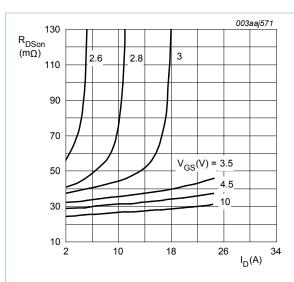


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

$$T_j = 25 \,^{\circ}C$$

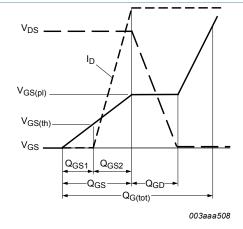


Fig. 14. Gate charge waveform definitions

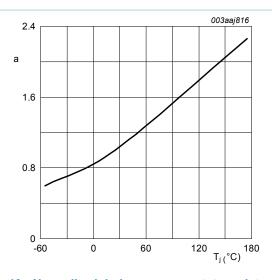


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon (25^{\circ}C)}}$$

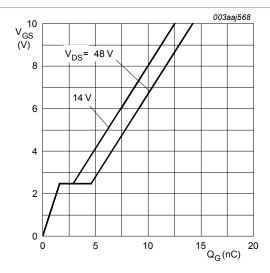


Fig. 15. Gate-source voltage as a function of gate charge; typical values

$$T_j = 25 \,^{\circ}C; I_D = 5A$$

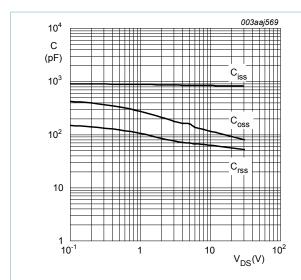
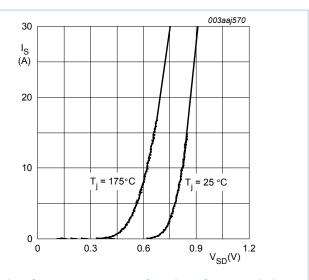


Fig. 16. Input, output and reverse transfer capacitances | Fig. 17. Source current as a function of source-drain as a function of drain-source voltage; typical values

$$V_{GS} = 0 V; f = 1MHz$$

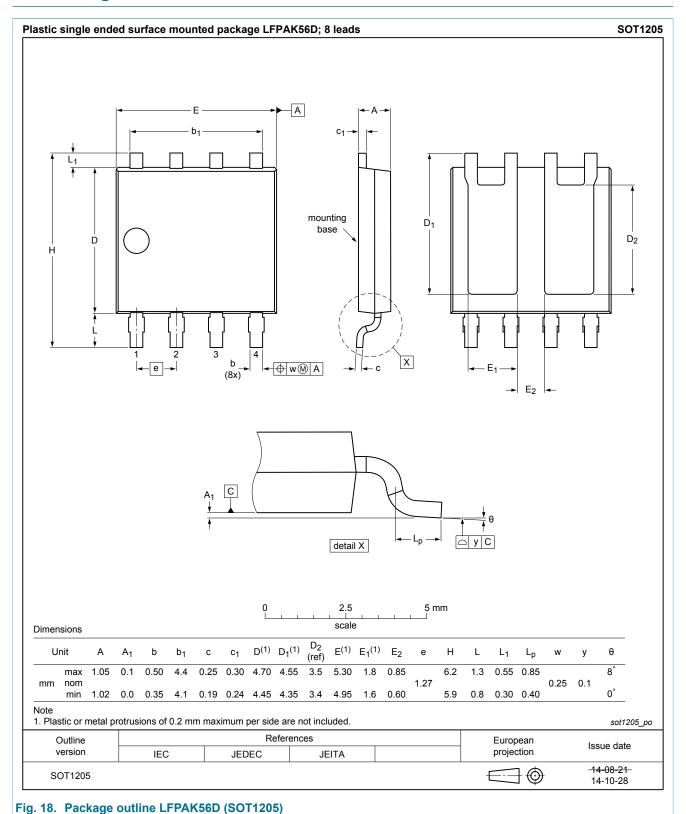


voltage; typical values

$$V_{GS} = 0 V$$

#### Dual N-channel 60 V, 35 m $\Omega$ logic level MOSFET

## 11. Package outline



### Dual N-channel 60 V, 35 mΩ logic level MOSFET

## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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